

COPY

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jau-Yuen SU

Group Art Unit: 3724

Serial No.: 09/394,918

Examiner: O. Flores-Sanchez

Filed: September 13, 1999

Atty. Dkt.: SUJA3001/REF/WKP

For: PROCESS FOR SAWING SUBSTRATE STRIP

**SUPPLEMENTAL AMENDMENT AND  
STATEMENT OF THE SUBSTANCE OF THE INTERVIEW**Commissioner for Patents  
Washington, D.C. 20231

Sir:

This is a supplemental response responsive to the Office Action mailed October 25, 2001 and the Interview of January 29, 2002 in the above application. Reconsideration of the application is respectfully requested in view of the following amendments and remarks.

IN THE CLAIMS

Please add the following new claim:

--13. (New) A process for sawing a substrate strip having a plurality of substrate areas by a saw machine, wherein the substrate has a longitudinal axis and a lateral axis and the substrate areas are grouped along the longitudinal axis, the process comprising the steps of:

providing a plurality of alignment marks around each of the individual substrate areas on the substrate strip;

providing a plurality of cutting marks around the substrate areas on the substrate strip such that two opposing longitudinal rows of the cutting marks are provided along